



Material Content Data Sheet



Sales Product Name		ICE3A1565		Issued		25. September 2017		
MA#		MA000981052						
Package		PG-DIP-8-13		Weight*		556.49 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.890	0.34	0.34	3396	3396
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		97	
	non noble metal	zinc	7440-66-6	0.215	0.04		386	
	non noble metal	iron	7439-89-6	4.297	0.77		7722	
wire	non noble metal	copper	7440-50-8	174.475	31.35	32.17	313529	321734
	noble metal	gold	7440-57-5	0.236	0.04	0.04	424	424
	encapsulation	organic material	carbon black	1333-86-4	1.099	0.20		1975
encapsulation	plastics	epoxy resin	-	35.536	6.39		63858	
	inorganic material	silicondioxide	60676-86-0	329.718	59.25	65.84	592500	658333
leadfinish	non noble metal	tin	7440-31-5	7.496	1.35	1.35	13470	13470
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1430	1430
glue	plastics	epoxy resin	-	0.101	0.02		182	
	noble metal	silver	7440-22-4	0.574	0.10	0.12	1031	1213
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com